

.050" AREA ARRAY SOCKET CSB SERIES

SPECIFICATIONS

Materials:
Insulator Material: Black Liquid Crystal Polymer
Contact Material: Beryllium Copper
Current Rating: 2A @ 80°C ambient
Operating Temp Range: -65°C to +125°C
Plating: Au over 50µ" (1,27µm) Ni
Contact Resistance: 10mΩ max
Insertion Depth: (1,79mm) .070" min/max
Insertion Force: 1.3oz (0,36N) avg
Withdrawal Force: 0.4oz (0,11N) avg

Mates with: MSB

Surface Mount!

High reliability Tiger-Eye contacts



Polarized notches

CONTACT PATENT PENDING

Optional polarized Alignment Pins

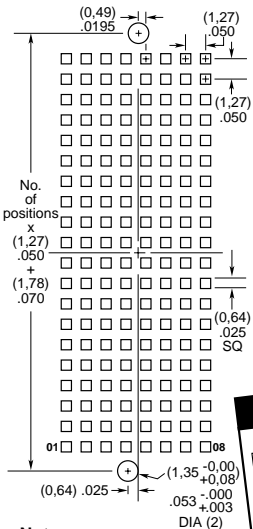
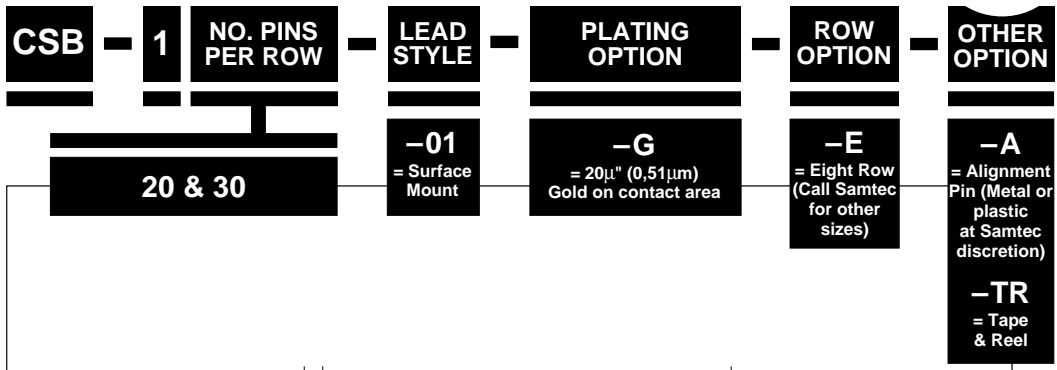
Note: Some sizes, styles and options are non-standard, non-returnable.

(1,27mm) .050" micro pitch

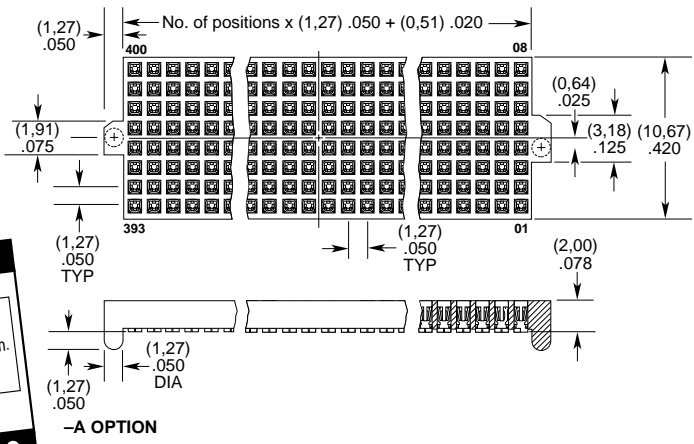
(2,00mm) .078" Low profile



Processing:
Max Processing Temp: 230°C for 60 seconds
SMT Lead Coplanarity: (0,15mm) .006" max
Typical Processing:
 • Water soluble paste compound
 • (0,15mm to 0,20mm) .006" to .008" paste thickness
 • 1:1 aperture
 • Mask or plug vias
 • Process like a BGA
 • X-ray inspection as required
Suggested PCB Layouts:
 Your specific layout may vary



TAPE & REEL AVAILABILITY
 No tooling charges.
 125 piece minimum order.
 Order any quantity above minimum.
 In-house design, manufacture.
 Quick turn-around.
 Call Samtec for specifications and ordering information.



Due to technical progress, all designs, specifications and components are subject to change without notice.